

Application

Wafer scale stencil printable B-stage die attach material



Features

- Good stencil printability.
- No shape change after printing
- Short time B-stageable (120C/10min)
- After B-staged material is stable (6months@25C)
- Good release performance from dicing film (standard and UV type).

Properties

Paste properties	Test method	SFX526A
Viscosity	CP51/5rpm	40Pa·s
Thixotropic index	CP51 0.5rpm/5rpm	2.3
Pot life	in syringe	168hr
	on mask	6hr
Shelf life	-40°C	1years

Printing condition	
Speed	25~50mm/s
Pressure	2kg
Stencil mask	50~100 μ m Thickness
Squeegee	Stainless/60°

B-stage properties		
B-stage condition	120°C/10min	
Pot life of after B-stage	6months/25C	
Die attaching condition	Die temperature	25~150°C
	Substrate temperature	150°C
	Pressure	0.5MPa
	Time	0.5sec

Post cure properties	Test method	SFX526A
Cure condition	RT~125°C/30min + 125°C/1hr + 125°C~165°C/30min + 165°C/2hr	
Tensile modulus	DMA25°C 0.2mmt	1500MPa
	DMA125°C 0.2mmt	500MPa
Glass transition temp.	TMA	120°C
Coefficient of thermal expansion	TMA -50°C~0°C	68ppm
	TMA 180°C~230°C	153ppm
Die share strength	2.5mm□ Si to Si Post cure	27MPa
	2.5mm□ Si to Si MSL1+IR260°C	23MPa

